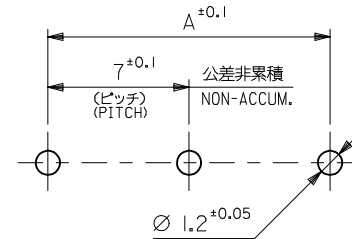
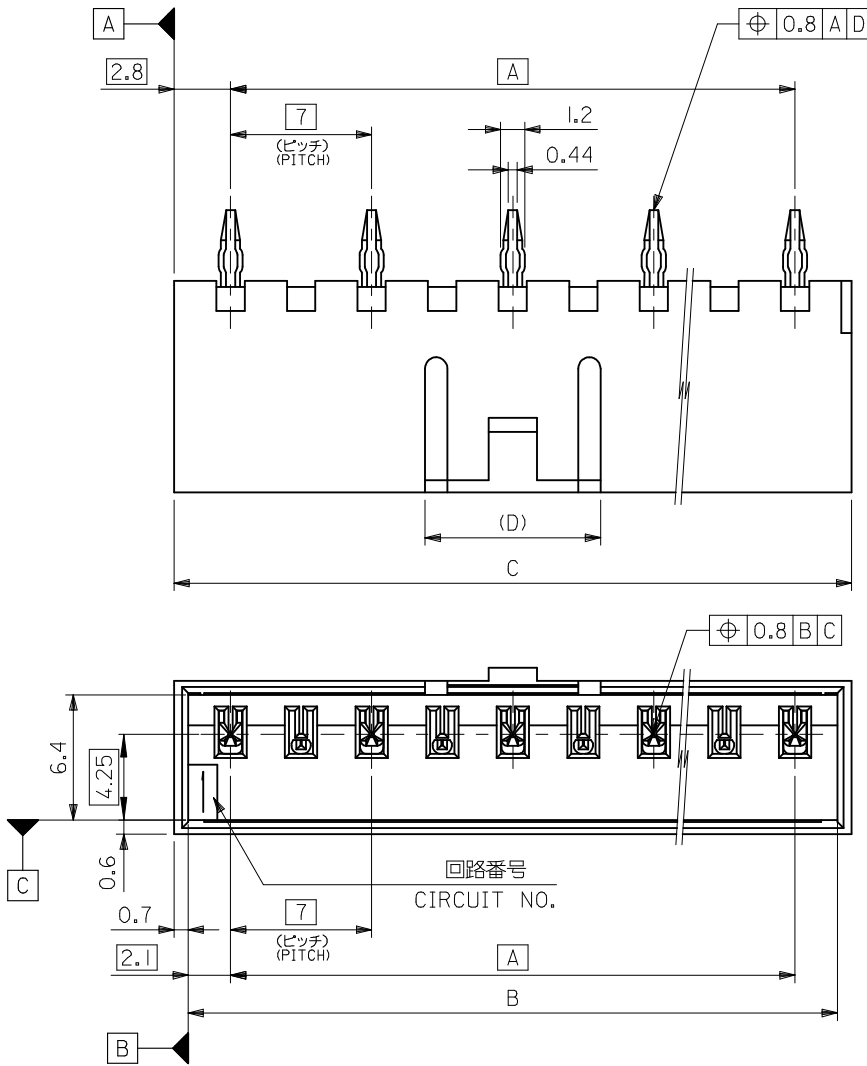
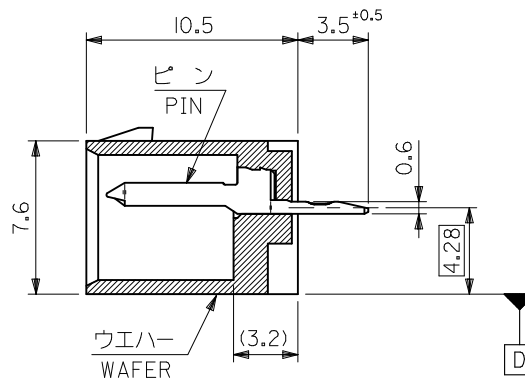


10 9 8 7 6 5 4 3 2 1



基板取付穴推奨寸法 (参考) (t=1.6)  
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)



8.7	54.6	53.2	49.0	53265-0820	8
				-0810	
	47.6	46.2	42.0	-0720	7
	40.6	39.2	35.0	-0620	6
	33.6	32.2	28.0	-0520	5
	26.6	25.2	21.0	-0420	4
8.7	19.6	18.2	14.0	-0320	3
				-0220	
6.1	12.6	11.2	7.0	53265-0210	2
(D)	C	B	A	TRAY PACKAGE	CKT. 極数
				ORDER No. オーダー番号	

注記 NOTES

1. 嵌合相手: 51067 シリーズ  
MATE WITH: 51067 SERIES

2. 材質  
MATERIAL

ウエハー: PBTP (ガラス15%入り)、UL94V-0  
WAFER: PBTP (G.F. 15%), UL94V-0

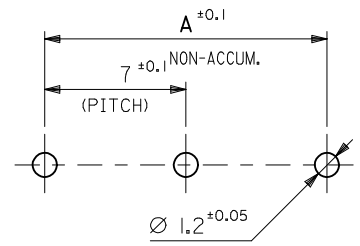
ピン: 53265-\*\*\*10 [リン青銅、錫メッキ (T=0.254)]  
PIN: [PHOS. BRO., PRE-TINNED (T=0.254)]

53265-\*\*\*20 [黄銅、錫メッキ (T=0.254)]  
[BRASS, PRE-TINNED (T=0.254)]

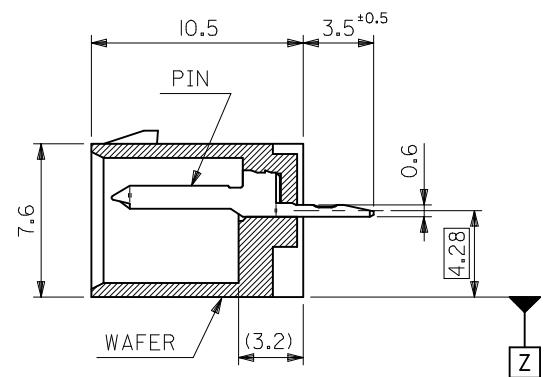
REVISED EC NO: J2009-1054 DRWN:MMABEI 2009/02/17 CHKD:HYAJIMA 2009/02/18 APPR:NUKITA 2009/02/18	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	MODEL NO.	
				MM ONLY	---	METRIC	53265-***0	
				THIRD ANGLE PROJECTION				
				7.0 WIRE TO BOARD CONN. WAFER ASS'Y (ST.)				
D	REV	10 UNDER	±0.2	DRAWN BY	DATE	TITLE	MOLEX INCORPORATED	
		10 OVER 30 UNDER	±0.25	K. ASAKAWA	'89/12/19	SD-53265-007		
		30 OVER	±0.30	H. HIRAMOTO	'93/06/29			
		ANGULAR	±3 °	M. FUKUSHIMA	'93/06/29			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	DOCUMENT NO.	SEE TABLE			SHEET NO.	1 OF 1
		SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

**NOTES**

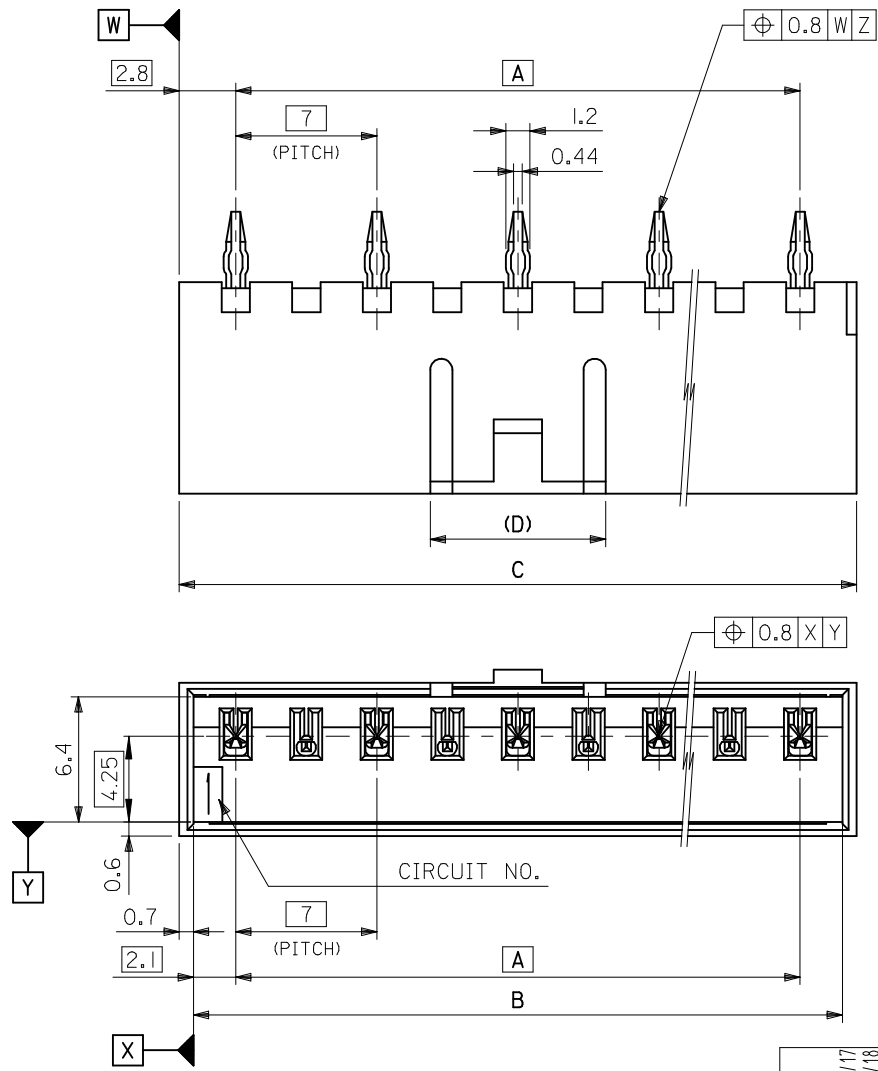
1. MATE WITHS : 51067 SERIES
2. MATERIAL  
 WAFER : PBTP (G.F.15%), UL94V-0  
 PIN : [PHOS.BRO., PRE-TINNED (t=0.254)]
3. COLOR OF WAFER  
 CORRESPONDS TO LAST DIGIT OF ENG. NO.  
 WHITE : 53265-\*\*10  
 BLACK : 53265-\*\*11  
 RED : 53265-\*\*12  
 YELLOW : 53265-\*\*13  
 BLUE : 53265-\*\*14



RECOMMENDED P.C. BOARD HOLE DIM. (REF.)  
(t=1.6)



8.7	54.6	53.2	49.0	53265-081*	8
↑	47.6	46.2	42.0	↑ -071*	7
	40.6	39.2	35.0	↑ -061*	6
	33.6	32.2	28.0	↑ -051*	5
↓	26.6	25.2	21.0	↓ -041*	4
8.7	19.6	18.2	14.0	↓ -031*	3
6.1	12.6	11.2	7.0	53265-021*	2
(D)	C	B	A	TRAY PACKAGE	CKT.
				3 ORDER No. オーダー番号	



REVISED EC NO: J2009-1054 DRWN:MMABEI 2009/02/17 CHKD:HYAJIMA 2009/02/18 APPR:NUKITA 2009/02/18	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 53265-***1*		
	10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	30 OVER ±0.30	DRAWN BY H. HIRAMOTO	DATE '94/01/10	TITLE 7.0 WIRE TO BOARD CONN. WAFER ASSY ST.			
	ANGULAR ±3 °			CHECKED BY M. FUKUSHIMA	DATE '94/01/11	MOLEX INCORPORATED			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			APPROVED BY M. FUKUSHIMA	DATE '94/01/11	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-53265-008	SHEET NO. 1 OF 1	